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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Garnik Taheri  
SERIAL NO.: 10/754,807  
FILING DATE: January 8, 2004  
TITLE: SINGLE IC PACKAGING SOLUTION FOR MULTI CHIP MODULES  
ART UNIT: 2822  
EXAMINER: Roy Karl Potter

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**CERTIFICATE OF MAILING**

I hereby certify that this paper is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: OIPE Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450, on the date printed below:

Date: 11/10/05Name: Michelle R. Crosby

Michelle R. Crosby

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**OFFICE OF INITIAL PATENT EXAMINATIONS  
CUSTOMER SERVICE CENTER  
COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, VA 22313-1450**

**REQUEST TO CORRECT FILING RECEIPT**


It is respectfully submitted that the Filing Receipt for the above-identified patent application has the following error. After "Assignment for Published Patent Application" should read: "SMART Modular Technologies Inc., a California Corporation", and NOT "SMART Modular Technologies Inc., a Delaware Corporation" as indicated on the Filing Receipt.

Attached is a copy of the (corrected) recorded Assignment and a red-line of the original filing receipt for your reference.

The Commissioner is hereby authorized to charge any additional fees or credit any overpayment to Deposit Account No. 50-1698. A duplicate copy of this page is enclosed.

Respectfully submitted,  
THELEN REID & PRIEST LLP

Dated: 11/10/05

  
Suvashis Bhattacharya  
Reg. No. 46,554

THELEN REID & PRIEST LLP  
P.O. Box 640640  
San Jose, CA 95164-0640  
(408) 292-5800



**COPY**

**UNITED STATES PATENT AND TRADEMARK OFFICE**

UNDER SECRETARY OF COMMERCE FOR INTELLECTUAL PROPERTY AND  
DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE

AUGUST 16, 2004

PTAS



\*102676321A\*

THELEN REID & PRIEST LLP  
THIERRY K. LO  
P.O. BOX 640640  
SAN JOSE, CA 95164

**UNITED STATES PATENT AND TRADEMARK OFFICE  
NOTICE OF RECORDATION OF ASSIGNMENT DOCUMENT**

THE ENCLOSED DOCUMENT HAS BEEN RECORDED BY THE ASSIGNMENT DIVISION OF THE U.S. PATENT AND TRADEMARK OFFICE. A COMPLETE MICROFILM COPY IS AVAILABLE AT THE ASSIGNMENT SEARCH ROOM ON THE REEL AND FRAME NUMBER REFERENCED BELOW.

PLEASE REVIEW ALL INFORMATION CONTAINED ON THIS NOTICE. THE INFORMATION CONTAINED ON THIS RECORDATION NOTICE REFLECTS THE DATA PRESENT IN THE PATENT AND TRADEMARK ASSIGNMENT SYSTEM. IF YOU SHOULD FIND ANY ERRORS OR HAVE QUESTIONS CONCERNING THIS NOTICE, YOU MAY CONTACT THE EMPLOYEE WHOSE NAME APPEARS ON THIS NOTICE AT 703-308-9723. PLEASE SEND REQUEST FOR CORRECTION TO: U.S. PATENT AND TRADEMARK OFFICE, ASSIGNMENT DIVISION, BOX ASSIGNMENTS, CG-4, 1213 JEFFERSON DAVIS HWY, SUITE 320, WASHINGTON, D.C. 20231.

RECORDATION DATE: 02/20/2004

REEL/FRAME: 014992/0159  
NUMBER OF PAGES: 2

BRIEF: ASSIGNMENT OF ASSIGNOR'S INTEREST (SEE DOCUMENT FOR DETAILS).

ASSIGNOR:

TAHERI, GARNIK

DOC DATE: 02/11/2004

ASSIGNEE:

SMART MODULAR TECHNOLOGIES, INC.  
4211 STARBOARD DRIVE  
FREMONT, CALIFORNIA 94538

SERIAL NUMBER: 10754807

FILING DATE: 01/08/2004

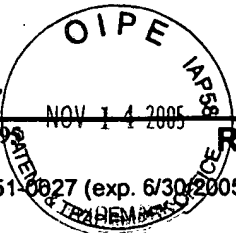
PATENT NUMBER:

ISSUE DATE:

TITLE: SINGLE IC PACKAGING SOLUTION FOR MULTI CHIP MODULES

014992/0159 PAGE 2

JOANN STEWART, EXAMINER  
ASSIGNMENT DIVISION  
OFFICE OF PUBLIC RECORDS



02-24-2004

IT

U.S. DEPARTMENT OF COMMERCE  
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OMB No. 0651-0027 (exp. 6/30/2005)

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To the Honorable Commissioner of Patents and Trademarks: Please Record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

Garnik Taheri

Additional name of conveying party(ies) attached? ☐ Yes ☒ No

## 2. Name and address of receiving party(ies)

Name: SMART Modular Technologies, Inc.

Internal Address: \_\_\_\_\_

Street Address: 4211 Starboard Drive

City: Fremont State: CA Zip: 94538

Additional Name(s) & address(es) attached? ☐ Yes ☒ No

## 3. Nature of conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution Date: February 11, 2004

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

10/754,807

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ NoRECEIVED  
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## 5. Name and address of party to whom correspondence concerning this document should be mailed:

Name: Thelen Reid & Priest LLP

Internal Address: \_\_\_\_\_

Street Address: P. O. Box 640640

City: San Jose State: CA Zip: 95164

6. Total number of applications and patents involved: ☒ 17. Total fee (37 CFR 3.41) ..... \$ 40

- ☐ Enclosed  
☒ Authorized to be charged to deposit account

## 8. Deposit account number:

50-1698

(Attach duplicate copy of this page if paying by deposit account)

02/23/2004 LMUELLER 00000093 501698 10754807

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## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Thierry K. Lo

Name of Person Signing

[Signature]  
Signature2/17/2004  
DateTotal number of pages including cover sheet, attachments, and documents: 2

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents & Trademarks, Box Assignments  
Washington, D.C. 20231

## ASSIGNMENT

WHEREAS, I, Garnik Taheri, a citizen of the United States of America, residing at 5424 Century Park Way, San Jose, CA 95111, have invented a "Single IC Packing Solution for Multi Chip Modules" for which I have executed application papers for a U.S. patent thereon which was filed on January 8, 2004, having Application No. 10/754,807; and

WHEREAS, SMART Modular Technologies, Inc., a California corporation, having a place of business located at 4211 Starboard Drive, Fremont, CA 94538, is desirous of acquiring the exclusive right, title and interest in and to said invention and in and to the Letters Patent to be granted and issued therefor in the United States of America and its territories and possessions, and all countries foreign thereto;

NOW, THEREFORE, for a valuable consideration, the receipt of which is hereby acknowledged, I, Garnik Taheri, do sell, assign, transfer and set over unto the said SMART Modular Technologies, Inc., its successors and assigns, the full and exclusive right, title and interest in and to said invention, and in and to any and all Letters Patent to be granted and issued therefor, not only for, to and in the United States of America, its territories and possessions, but also for, to and in all other countries including all priority rights under the International Convention; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said SMART Modular Technologies, Inc., its successors and assigns, in accordance with this Assignment.

G. Taheri  
Garnik Taheri

02/11/04  
Date

Excel \_\_\_\_\_ Date \_\_\_\_\_